nexperia

Quarterly Reliability Monitoring Results

Quarters: Q3/2021 to Q4/2022

Based on structural similarity

| Supplier | | User Part Number | | | | | | |
|--------------------------------------------------------------------------------------------|----------------------------------------------------------------|-----------------------------------------------------------------------------------------------------|-----------------------|-----------|------------|-----------|--|-----------------------------------------|
| Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test | | PTVS10VS1UTR Part Description | | | | | | |
| | | | | | | | | Nexperia DHAM Protection SMD package |
| | | Test Conditions | Duration | # Lots | # Quantity | # Rejects | | |
| | | | TEST | | | | | |
| | | | Pre- and Post-Stress | | | | | |
| # E1 | Electrical Test | Tamb = 25 °C | N/A | see below | all parts | see below | | |
| | | JESD22-A113 Bake Tamb = 125 °C | 24 hours | | | | | |
| # A1 | PC Preconditioning | Soak Tamb = 85 °C, RH = 85% Reflow soldering | 168 hours 3 cycles | 438 | 24630 | 0 | | |
| | HTRB High Temperature Reverse | MIL-STD-750-1 M1038 Method A Tj = Tjmax, Vr = 100% of max. datasheet | | | | | | |
| # B1 | Bias | reverse voltage | 1000 hours | 166 | 10040 | 0 | | |
| # A4 | TC Temperature Cycling | JESD22-A104 -65 °C to Tjmax, not to exceed 150°C | 1000 cycles | 131 | 7760 | 0 | | |
| # A3 or | UHAST Unbiased HAST | JESD22-A118 Tamb = 130 °C, RH = 85 % | — 96 hours | 131 | 7760 | 0 | | |
| # A3 alt | AC Autoclave | JESD22-A102 Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia) | 90 110015 | | | | | |
| # A2 alt | H3TRB High Humidity High Temperature Reverse Bias | JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage ^[1] | 1000 hours | 131 | 7760 | 0 | | |
| # A5 | IOL Intermittent Operating Life | MIL-STD-750 Method 1037 ton = toff, devices powered to insure ΔTj = 100 °C for 15000 cycles | 1000 hours | n.a. | n.a. | n.a. | | |
| # C8 | RSH Resistance to Solder Heat | JESD22-A111 260 °C ± 5 °C | 10 s | 45 | 1350 | 0 | | |
| # C10 | SD Solderability | J-STD-002 | | 111 | 1110 | 0 | | |

[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Wafer Fab | Technology | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|------------------|------------|----------|---------|--------------------|------------|
| Nexperia DHAM | Protection | 10040 | 0 | 0,42 | 2,36E+09 |

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